

06-15-2004



U.S.

ICE

102766298

Case Docket No. ABE-024U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

6.8.04

RECORDATION FORM COVER SHEET
PATENTS ONLYTo the Honorable Commissioner of Patents and Trademarks.
Please record the attached original documents or copy thereof.

1. Name of conveying parties:

Shinichi TOMITAAdditional name(s) of conveying party(ies) attached? Yes ___ No XX

2. Name and address of receiving party:

Name: Sumitomo Mitsubishi Silicon Corporation

Internal Address:

Street Address: 1-2-1 Shibaura, Minato-ku, Tokyo 105-8634, JapanAdditional name(s) & address(es) attached? Yes ___ No XX

3. Nature of conveyance:

XX Assignment

___ Merger

___ Security Agreement

___ Change of Name

___ Other: ___

Execution Date: May 18, 2004

4. Title:

SOI SUBSTRATE AND MANUFACTURING METHOD THEREOF5. Application number(s) or patent number(s): 10862439If this document is being filed together with a new application, the
execution date of the application is: May 18, 2004

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? Yes ___ No XX17510 U.S. PTO
10/862439

06/09/2004 LWONDIM1 00000075 10862439

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PATENT
REEL: 015445 FRAME: 0068

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6. Name and address of party to whom correspondence concerning document should be mailed:

Name: KUBOVCIK & KUBOVCIK
The Farragut Building
Suite 710
900 17th Street, N.W.
Washington, D.C. 20006

7. Total number of applications and patents involved:

1

8. Total fee (37 CFR 3.41). \$ 40.00

☒ Enclosed

☐ Authorized to be charged to Deposit Account


9. Deposit Account No.: 111833

10. In the event any additional fees are required, please charge our Deposit Account No.: 111833.

11. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Keiko Tanaka Kubovcik
Name of Person Signing


Signature

June 8, 2004
Date

40,428
Registration Number

Total number of pages, including cover sheet, attachments, and document:

3

Atty. Docket No. ABE-024

KTK/jbf

17510 U.S. PTO
10/862439



U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

(Insert ASSIGNEE'S
Name(s) Address(es))

Sumitomo Mitsubishi Silicon Corporation
1-2-1 Shibaura, Minato-ku, Tokyo 105-8634, Japan

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of Invention)

SOI substrate and manufacturing method thereof

(*If the assignment is
being filed after the
filing of the
application, this section
must be completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

*filed on _____, Serial No. _____.
(Kubovcik & Kubovcik is hereby authorized to insert the series code, serial number and/or filing date, when known)

and to all Letters Patent of the United States to be obtained thereof on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with this application and any continuing, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(signatures)

<u>Shinichi Tomita</u> (SIGNATURE)	<u>Shinichi Tomita</u> (TYPE NAME)	<u>18/5/2004</u> (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)

NO LEGALIZATION REQUIRED

08/00